L Number	Hits	Search Text	DB	Time stamp
-	4100	134/137,140,149,153,157,201,902.ccls.	USPAT;	2004/10/13 13:57
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	,
			IBM_TDB	
-	3083	134/99.1,102.1,137,140,149,153,157,201.ccls.	USPAT;	2004/10/13 13:58
		,	US-PGPUB;	
	İ		EPO; JPO;	
1			DERWENT;	
	4839	124/00 1 102 1 127 140 140 152 157 201 000	IBM_TDB	
-	4039	134/99.1,102.1,137,140,149,153,157,201,902.ccls.	USPAT;	2004/10/13 14:12
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	920	134/99.1,102.1,137,140,149,153,157,201,902.ccls. and	USPAT;	2004/10/13 14:12
		((semiconductor or substrate or wafer) with (rotat\$3 or rotary))	US-PGPUB;	2004/10/13 14.12
		(1-1	EPO; JPO;	
			DERWENT:	
1			IBM TDB	
-	475	(134/99.1,102.1,137,140,149,153,157,201,902.ccls. and	USPAT;	2004/10/13 14:12
		((semiconductor or substrate or wafer) with (rotat\$3 or rotary)))	US-PGPUB;	2007/10/10 14.12
	/ .	and (chuck or holder)	EPO; JPO;	
1		, · · · · · · · · · · · · · · · · · · ·	DERWENT;	
			IBM_TDB	
ļ -	1685	((134/99.1,102.1,137,140,149,153,157,201,902.ccls. and	USPAT;	2004/10/13 14:12
		((semiconductor or substrate or wafer) with (rotat\$3 or rotary)))	US-PGPUB;	
		and (chuck or holder)) or 118/52.ccls.	EPO; JPO;	
	i		DERWENT;	
			IBM_TDB	
-	6031	134/99.1,102.1,137,140,149,153,157,201,902.ccls. or	USPAT;	2004/10/13 14:12
		118/52.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	4540	(424/00 4 400 4 407 440 440 450 457 004 000)	IBM_TDB	
_	1513	(134/99.1,102.1,137,140,149,153,157,201,902.ccls. or	USPAT;	2004/10/13 14:13
		118/52.ccls.) and ((semiconductor or substrate or wafer) with (rotat\$3 or rotary))	US-PGPUB;	
		(iotatęs of iotary))	EPO; JPO;	
	i		DERWENT;	
<u>-</u>	859	((134/99.1,102.1,137,140,149,153,157,201,902.ccls. or	IBM_TDB	2004/40/40 44:40
	009	118/52.ccls.) and ((semiconductor or substrate or wafer) with	USPAT;	2004/10/13 14:12
		(rotat\$3 or rotary))) and (chuck or holder)	US-PGPUB;	
	ļ	(DERWENT:	
			IBM_TDB	
-	614	(134/99.1,102.1,137,140,149,153,157,201,902.ccls. or	USPAT;	2004/10/13 14:13
		118/52.ccls.) and ((semiconductor or substrate or wafer) with	US-PGPUB;	2007/10/13 14.13
		(rotat\$3 or rotary) with (chuck or holder))	EPO; JPO;	
		· · · · · · · · · · · · · · · · · · ·	DERWENT;	
ļ			IBM_TDB	
-	330	((134/99.1,102.1,137,140,149,153,157,201,902.ccls. or	USPAT;	2004/10/13 14:13
j		118/52.ccls.) and ((semiconductor or substrate or wafer) with	US-PGPUB;	
		(rotat\$3 or rotary) with (chuck or holder))) and liquid and gas	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	11	kurt near2 langen	USPAT;	2004/10/13 14:14
	1		US-PGPUB;	
	ļ		EPO; JPO;	
	i		DERWENT;	
			IBM_TDB	